

SCES172D-DECEMBER 1998-REVISED SEPTEMBER 2004

DGG, DGV, OR DL PACKAGE

•	Member of the Texas Instruments Widebus™
	Family

- Operates From 1.65 V to 3.6 V
- Max t_{nd} of 3.8 ns at 3.3 V
- ±12-mA Output Drive at 3.3 V
- Outputs Have Equivalent 26-Ω Series **Resistors, So No External Resistors Are** Required
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION/ORDERING INFORMATION

This 18-bit universal bus driver is designed for 1.65-V to 3.6-V V_{CC} operation.

Data flow from A to Y is controlled by the output-enable (OE) input. The device operates in the transparent mode when the latch-enable (LE) input is low. The A data is latched if the clock (CLK) input is held at a high or low logic level. If LE is high, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When OE is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The outputs, which are designed to sink up to 12 mA, include equivalent 26- Ω resistors to reduce overshoot and undershoot.

(TOP VIEW)							
			٦				
NC	1	U 56	GND				
NC	2	55] NC				
Y1 [3	54	A 1				
GND [4	53	GND				
Y2 [5	52	A 2				
Y3 [6	51] A3				
V _{CC}	7	50]v _{cc}				
Y4 [8	49	A 4				
Y5 [9	48	A 5				
Y6	10	47	A 6				
GND [11	46	GND				
Y7 [12	45	A 7				
Y8 [13	44	A 8				
Y9	14	43	A 9				
Y10	15	42	A 10				
Y11 [16	41	A 11				
Y12 [17	40	A12				
GND [18	39	GND				
Y13	19	38	A13				
Y14 [20	37	A 14				
Y15 [21	36	P '				
V _{CC} [22	35	P 00				
Y16 [23	34	A16				
Y17 [24	33	A17				
GND [25	32	GND				
Y18	26	31	P				
OE [27	30]сгк				
LE [28	29] GND				
			_				

NC - No internal connection

PACKAGE⁽¹⁾ **ORDERABLE PART NUMBER TOP-SIDE MARKING** TA Tube SN74ALVC162834DL SSOP - DL ALVC162834 Tape and reel SN74ALVC162834DLR -40°C to 85°C TSSOP - DGG Tape and reel SN74ALVC162834GR ALVC162834 TVSOP - DGV SN74ALVC162834VR VC2834 Tape and reel

ORDERING INFORMATION

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SN74ALVC162834 **18-BIT UNIVERSAL BUS DRIVER** WITH 3-STATE OUTPUTS

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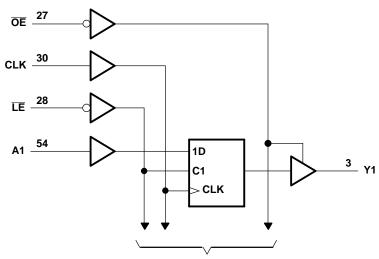
FUNCTION TABLE

	INP	OUTPUT		
ŌE	LE	CLK	Α	Y
Н	Х	Х	Х	Z
L	L	Х	L	L
L	L	Х	Н	Н
L	Н	\uparrow	L	L
L	Н	\uparrow	Н	Н
L	Н	Н	Х	Y ₀ ⁽¹⁾
L	Н	L	Х	Y ₀ ⁽¹⁾ Y ₀ ⁽²⁾

Output level before the indicated steady-state input conditions were established, provided that CLK is high before LE goes high
 Output level before the indicated steady-state input conditions

LOGIC DIAGRAM (POSITIVE LOGIC)

were established



To 17 Other Channels



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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			M	IN	MAX	UNIT
V _{CC}	Supply voltage range		-().5	4.6	V
VI	Input voltage range ⁽²⁾		-().5	4.6	V
Vo	Output voltage range ⁽²⁾⁽³⁾		-().5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V ₁ < 0			-50	mA
I _{OK}	Output clamp current	V _O < 0			-50	mA
I _O	Continuous output current				±50	mA
	Continuous current through each V _C	_C or GND			±100	mA
		DGG package			64	
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGV package			48	°C/W
		DL package			56	
T _{stg}	Storage temperature range		-	65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This value is limited to 4.6 V maximum.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			MIN	MAX	UNIT	
V_{CC}	Supply voltage		1.65	3.6	V	
		V _{CC} = 1.65 V to 1.95 V	$0.65 imes V_{CC}$			
VIH	High-level input voltage	V_{CC} = 2.3 V to 2.7 V	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$		
V _{IL}	Low-level input voltage	V_{CC} = 2.3 V to 2.7 V		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
VI	Input voltage		0	3.6	V	
Vo	Output voltage		0	V_{CC}	V	
		V _{CC} = 1.65 V		-2		
	High lovel output ourrent	$V_{CC} = 2.3 V$		-6	mA	
I _{OH}	High-level output current	$V_{CC} = 2.7 V$		-8	ША	
		$V_{CC} = 3 V$		-12		
		V _{CC} = 1.65 V		2		
	Low-level output current	$V_{CC} = 2.3 V$		6	m۸	
I _{OL}		$V_{CC} = 2.7 V$		8	mA	
		$V_{CC} = 3 V$		12		
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

 All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	V _{cc}	MIN TYP ⁽¹⁾	MAX	UNIT	
		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2			
		I _{OH} = -2 mA	1.65 V	1.2			
		I _{OH} = -4 mA	2.3 V	1.9			
V _{OH}			2.3 V	1.7		V	
		I _{OH} = -6 mA	3 V	2.4			
		I _{OH} = -8 mA	2.7 V	2			
		I _{OH} = -12 mA	3 V	2			
		I _{OL} = 100 μA	1.65 V to 3.6 V		0.2		
		$I_{OL} = 2 \text{ mA}$	1.65 V		0.45		
		$I_{OL} = 4 \text{ mA}$	2.3 V		0.4		
V _{OL}		1 – 6 m A	2.3 V		0.55	V	
		I _{OL} = 6 mA	3 V		0.55		
		I _{OL} = 8 mA	2.7 V		0.6		
		$I_{OL} = 12 \text{ mA}$	3 V		0.8		
I _I		$V_{I} = V_{CC} \text{ or } GND$	3.6 V		±5	μA	
I _{OZ}		$V_{O} = V_{CC}$ or GND	3.6 V		±10	μA	
I _{CC}		$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	3.6 V		40	μA	
ΔI_{CC}		One input at V_{CC} - 0.6 V, Other inputs at V_{CC} or GND	3 V to 3.6 V		750	μA	
C	Control inputs	$\lambda = \lambda = \alpha C N D$	221/	4		ъĘ	
Ci	Data inputs	$V_{I} = V_{CC} \text{ or } GND$	3.3 V	5.5		pF	
Co	Outputs	$V_{O} = V_{CC} \text{ or } GND$	3.3 V	7		pF	

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(1) All typical values are at $V_{CC} = 3.3$ V, $T_A = 25^{\circ}C$.

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				V _{CC} =	1.8 V	V _{CC} = 1 ± 0.2	2.5 V 2 V	V _{CC} =	2.7 V	V _{CC} = ± 0.3	3.3 V 3 V	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency				(1)		150		150		150	MHz
	Dulas duration	LE low		(1)		3.3		3.3		3.3		
t _w	Pulse duration	CLK high or low		(1)		3.3		3.3		3.3		ns
		Data before CLK1		(1)		2.1		2.1		1.7		
t _{su}	Setup time	Data before LE↑	CLK high	(1)		2.3		2.3		1.9		ns
		Data before LE	CLK low	(1)		1.9		1.9		1.5		
		Data after CLK↑ (1) 0.6		0.6		0.7						
t _h	Hold time	Data after LE↑	CLK high or low	(1)		0.8		0.8		0.9		ns

(1) This information was not available at the time of publication.



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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	V _{CC} = ²	1.8 V	V _{CC} = ± 0.2	2.5 V 2 V	V _{CC} =	2.7 V	V _{CC} = 2 ± 0.3	3.3 V 3 V	UNIT
	(INPUT)	(OUTPUT)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			(1)		150		150		150		MHz
	A			(1)	1	5.2		5	1	4.2	
t _{pd}	LE	Y		(1)	1.3	6		6.8	1.3	5.8	ns
	CLK			(1)	1.4	6.8		6.1	1.4	5.4	
t _{en}	OE	Y		(1)	1.4	6.3		6.5	1.5	5.9	ns
t _{dis}	OE	Y		(1)	1	4.4		5.2	1.8	5	ns

(1) This information was not available at the time of publication.

SWITCHING CHARACTERISTICS

from 0°C to 65°C, $C_L = 50 \text{ pF}$

PARAMETER	FROM	TO	V _{CC} = 3 ± 0.15	8.3 V 5 V	UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	
	A		1.4	3.9	
t _{pd}	LE	Y	1.8	5.5	ns
	CLK		1.8	5.2	

OPERATING CHARACTERISTICS

 $T_A = 25^{\circ}C$

	PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT
C	Dower dissipation consoitance	Outputs enabled	C = 0.5 = 10 MHz	(1)	38	41	рF
Cpd	Power dissipation capacitance	Outputs disabled	$C_{L} = 0, f = 10 \text{ MHz}$	(1)	13	15	рг

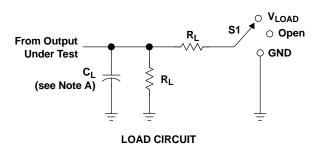
(1) This information was not available at the time of publication.

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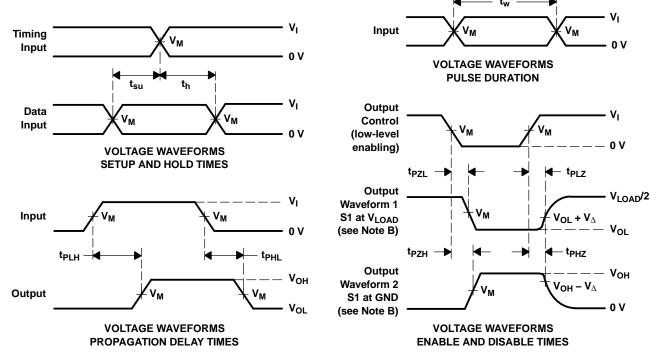
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PARAMETER MEASUREMENT INFORMATION



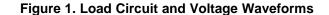
TEST	S1
t _{pd}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

N	IN	PUT	V	V	6	Р	v
V _{cc}	VI	t _r /t _f	V _M	V _{LOAD}	C∟	RL	V_{Δ}
1.8 V	V _{CC}	≤2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.





11-Sep-2016

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ALVC162834DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVC162834	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

11-Sep-2016

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice. В.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15). C.
 - D. Falls within JEDEC MO-118

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